



SWTEST

PROBE TODAY, FOR TOMORROW

2024 CONFERENCE

Probe Heads for Optical Wafer-Level Testing

Keystone
photonics

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Florian Rupp

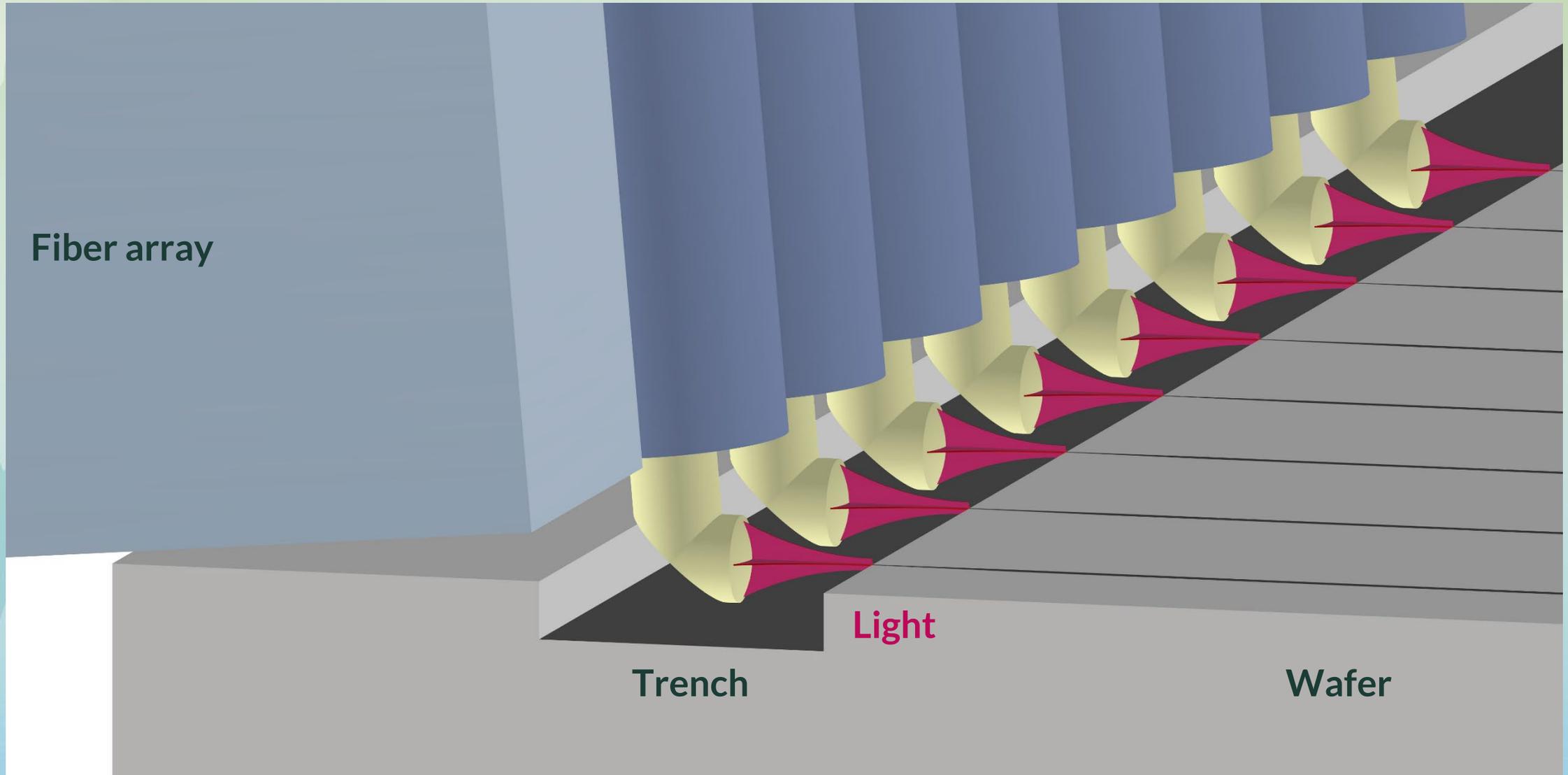
Andrés Machado

Keystone Photonics GmbH

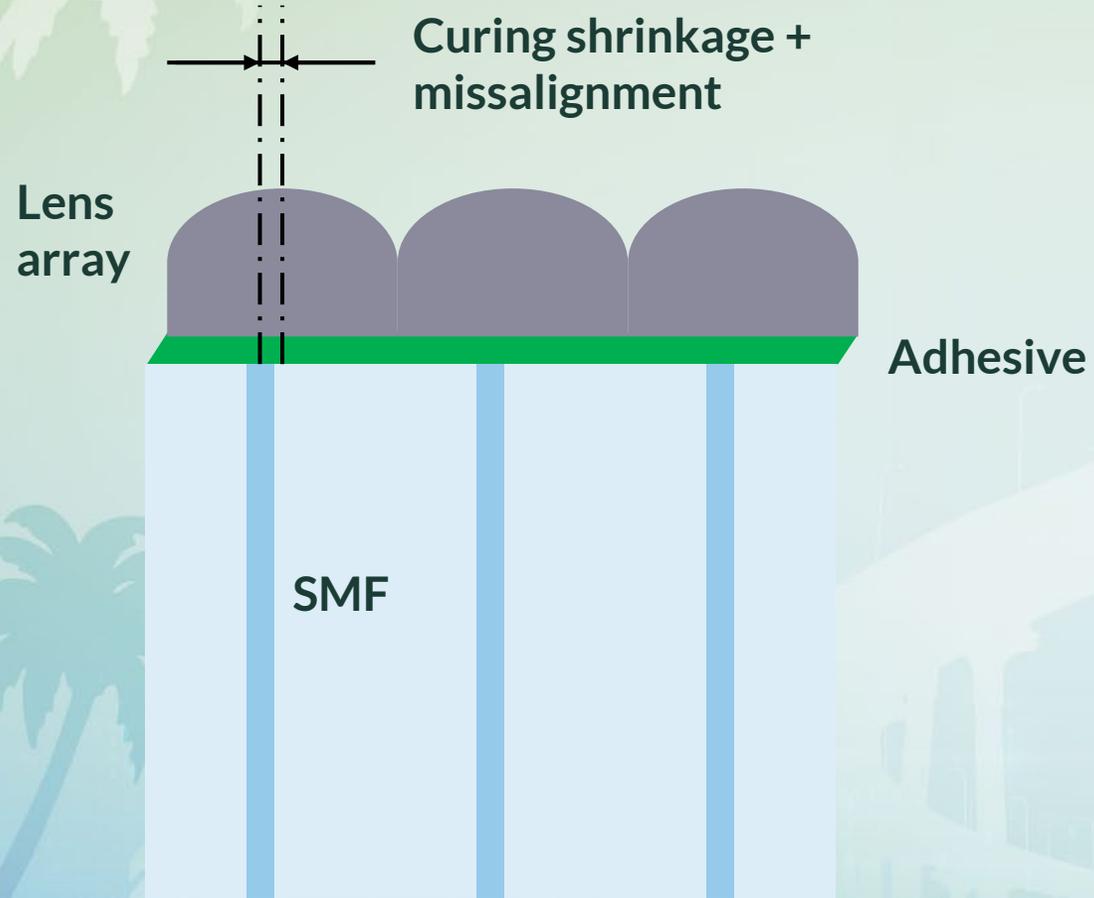
Content

- **In-situ fabrication of micro-optics**
- **Performance and reproducibility**
- **Optical wafer-level testing**
 - Surface coupling
 - Trench coupling
- **New developments**
 - Ultra dense pitch for AI
 - Integrated sensor functionality for production
 - Cryo and broadband testing for quantum applications

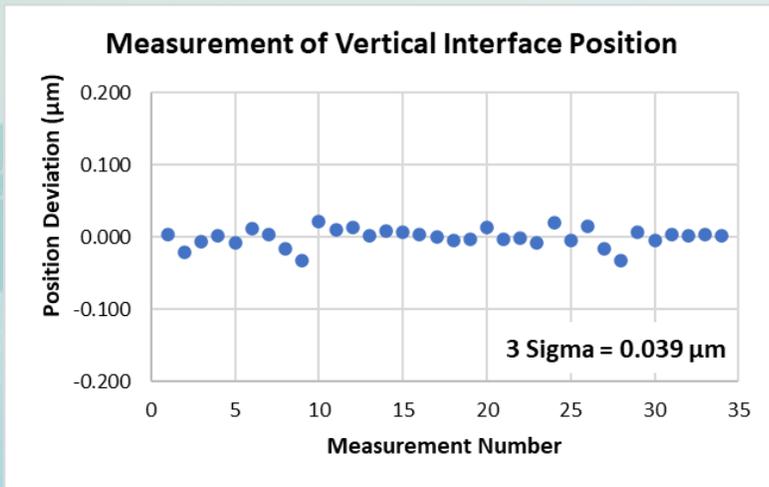
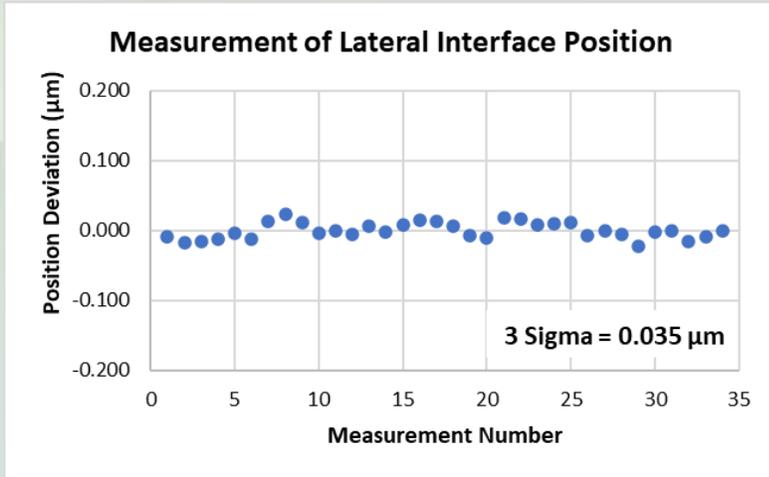
Our solution for optical wafer-level testing



Conventional lens array alignment

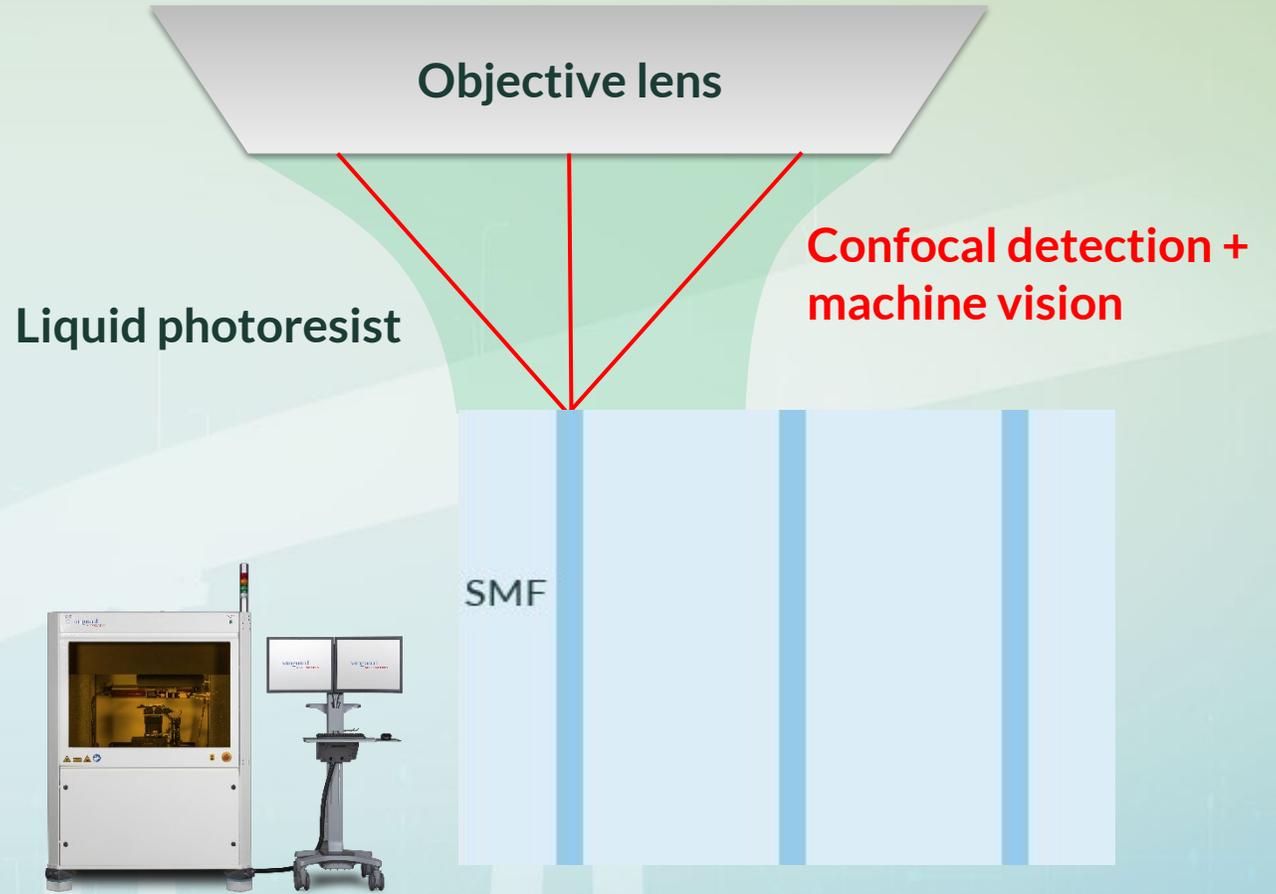


In-situ fabrication



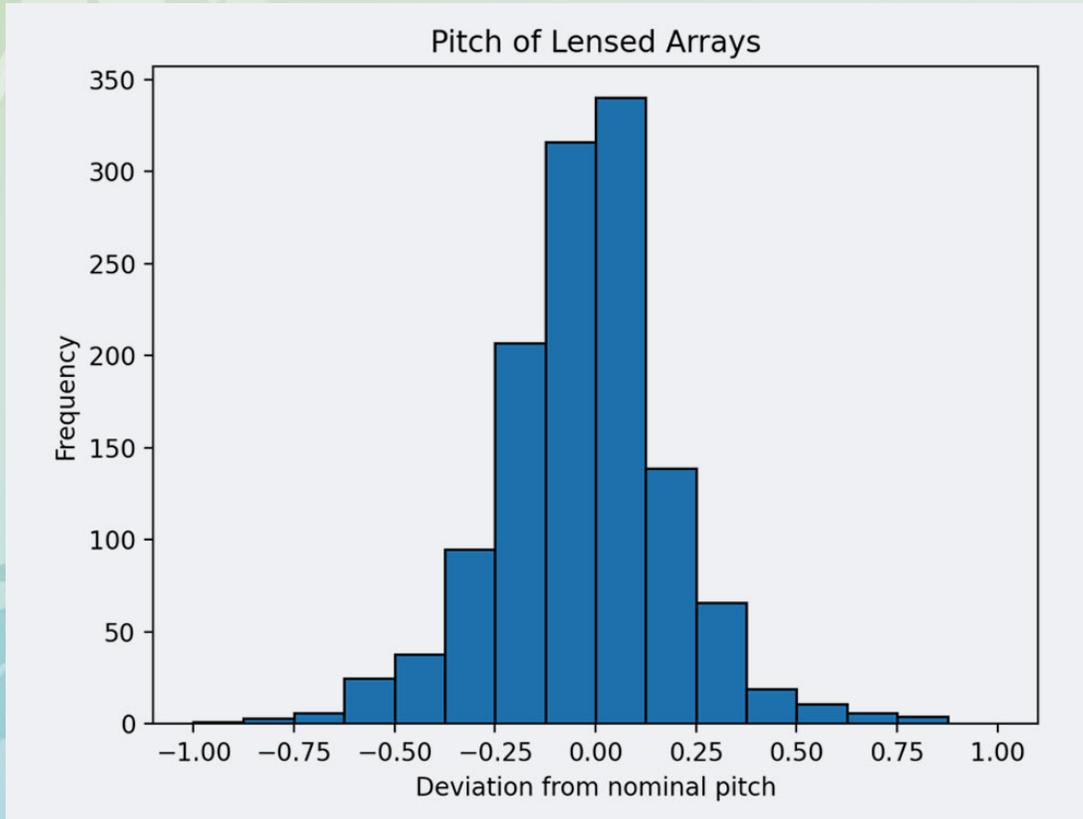
Philipp Dietrich

Data: Vanguard Automation

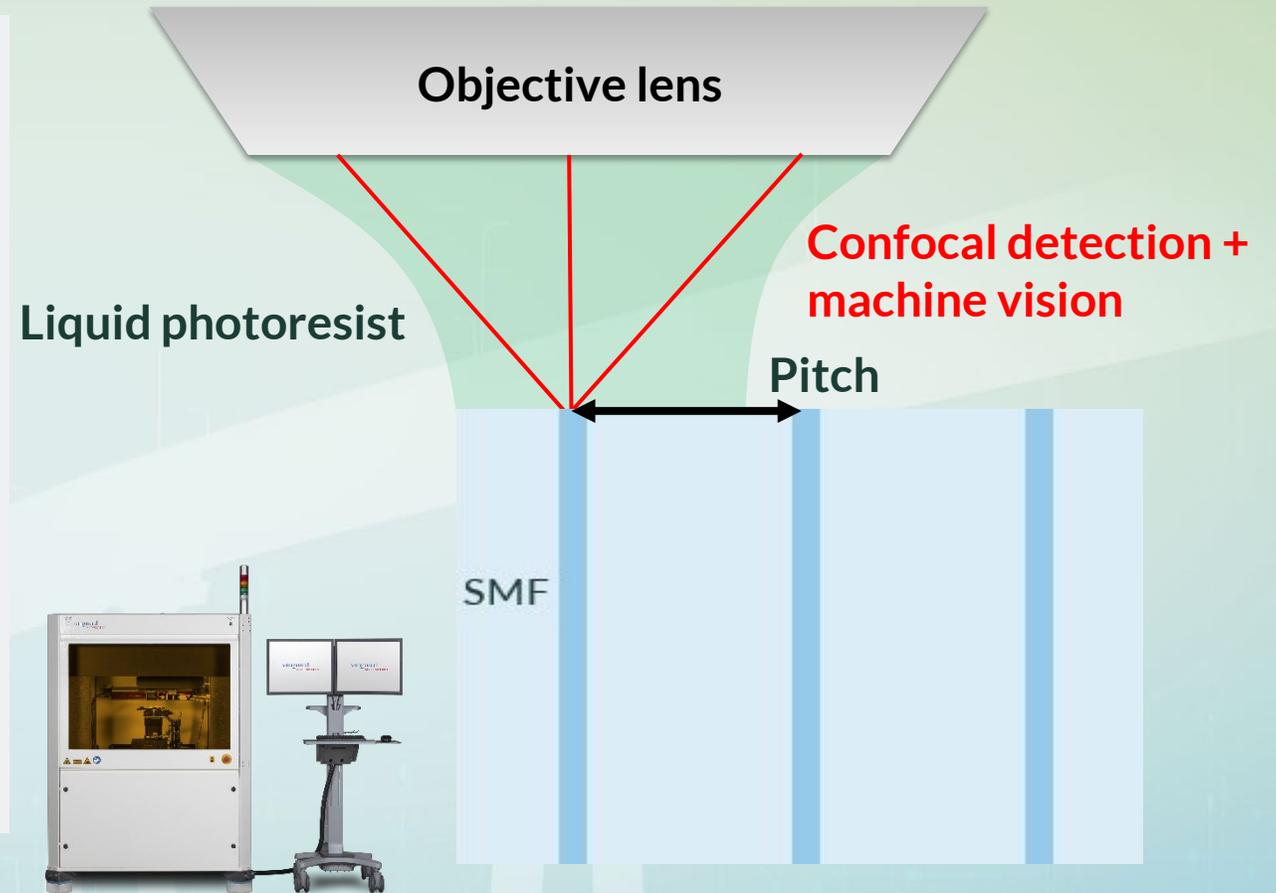


Sonata1000

In-situ fabrication

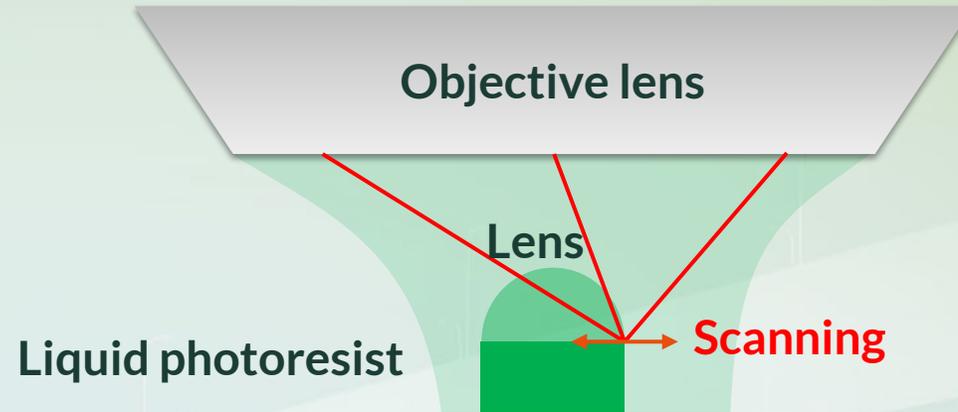


Data: Vanguard Automation



Sonata1000

In-situ fabrication



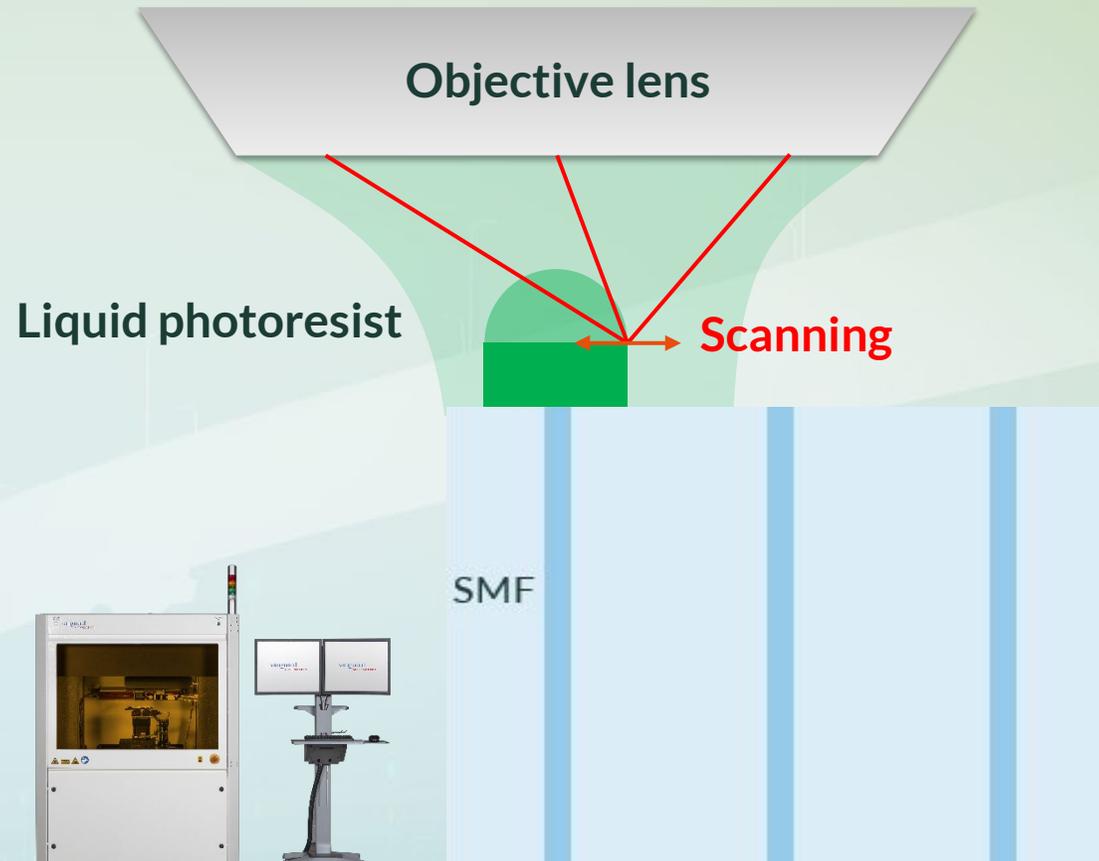
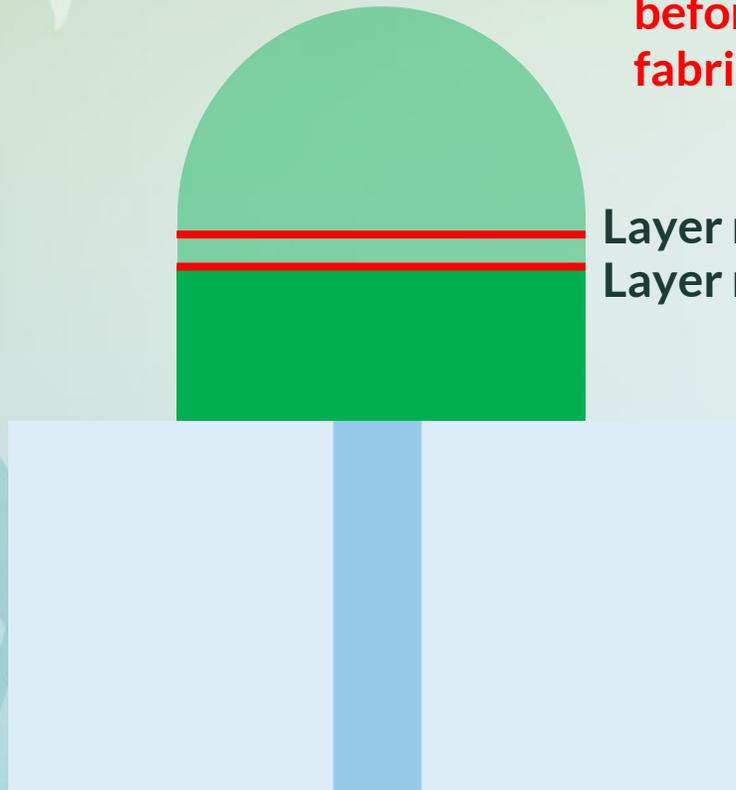
Sonata1000

SMF

**Very same laser =>
detection missalignment
and fabrication
missalignment cancel out!**

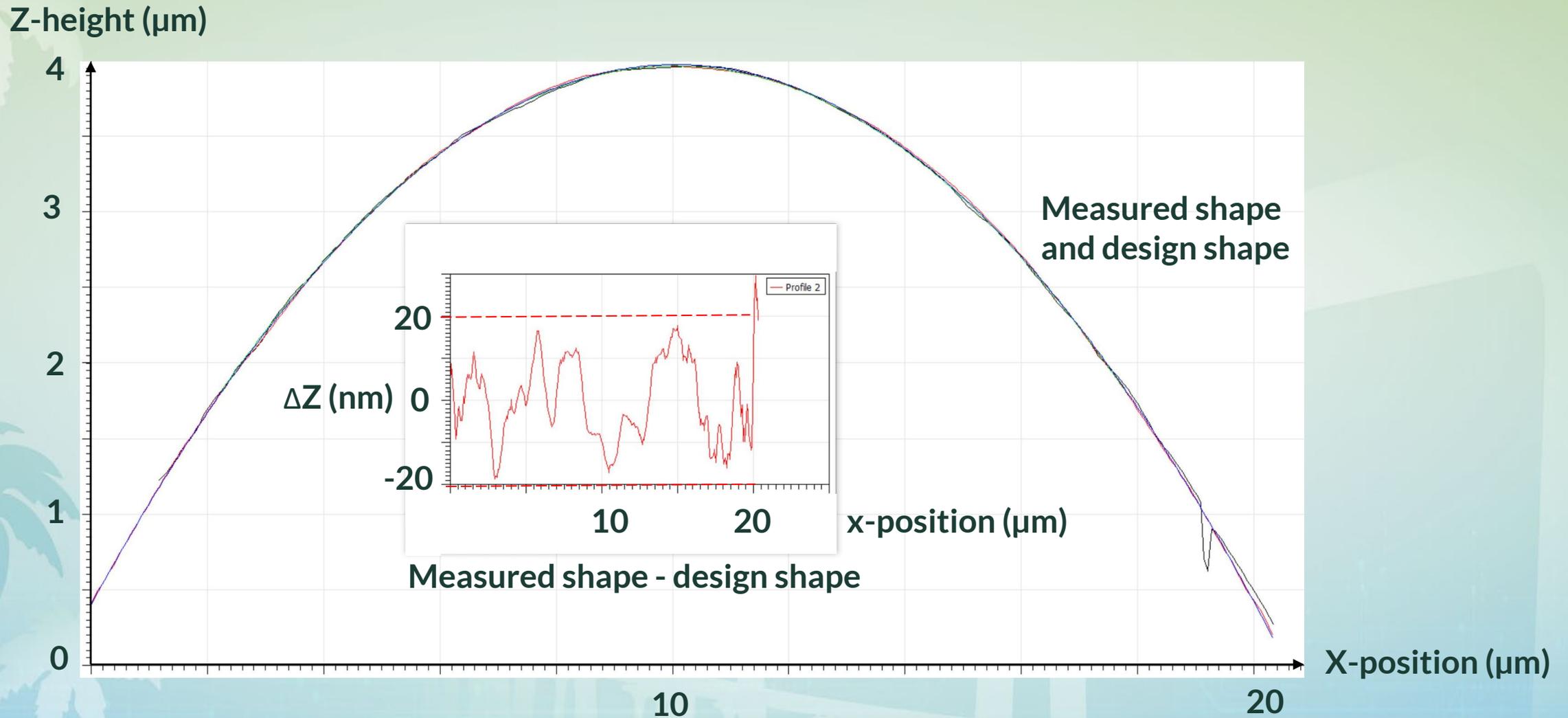
What about curing shrinkage?

Layer n is cured and shrunken before layer n + 1 is fabricated!



Sonata1000

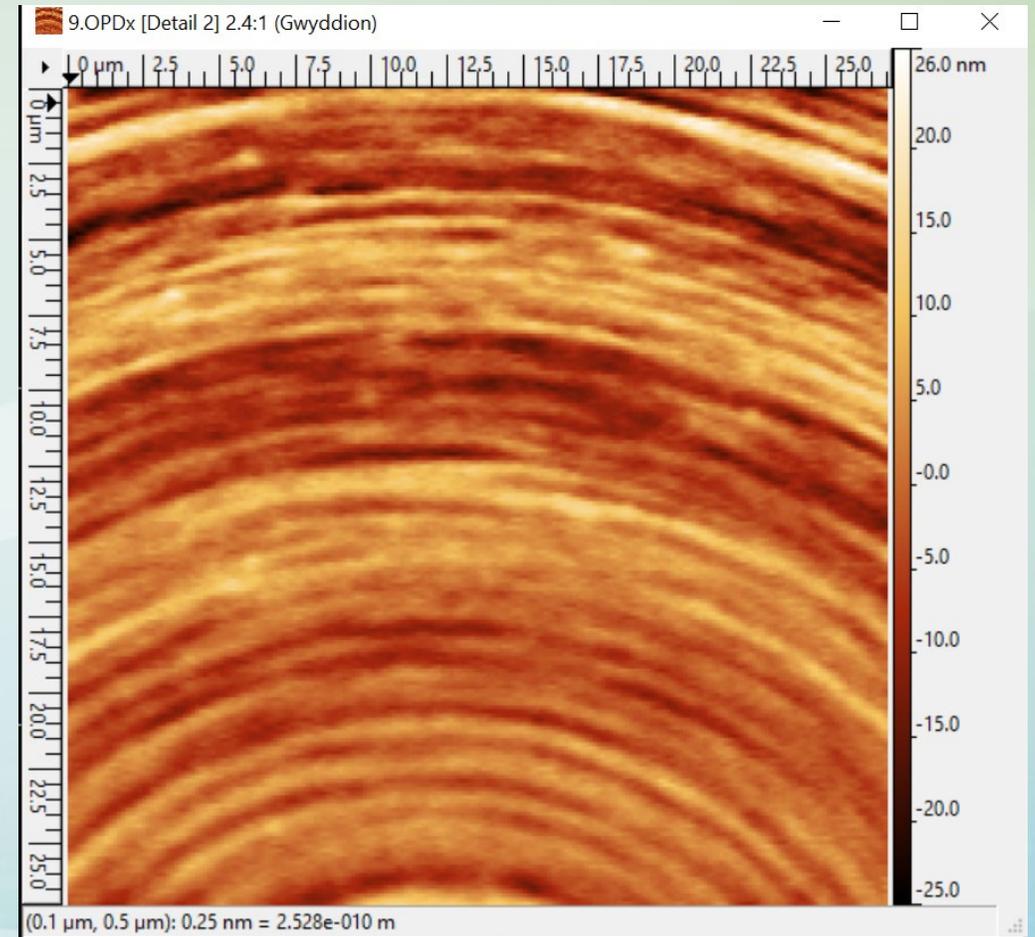
Fabrication accuracy



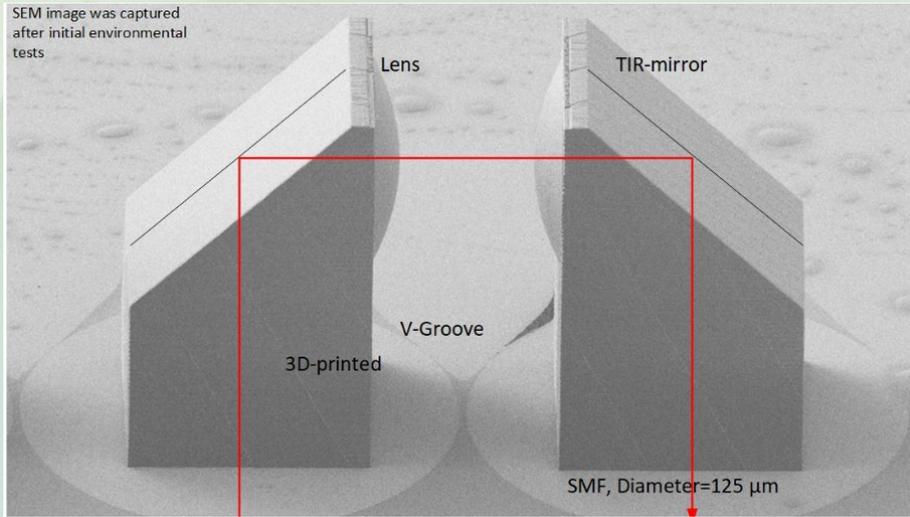
Roughness

10 nm RMS

- Measured with Bruker ContourX-100
- USI mode and NA=0.8
- AFM measures 12 nm RMS



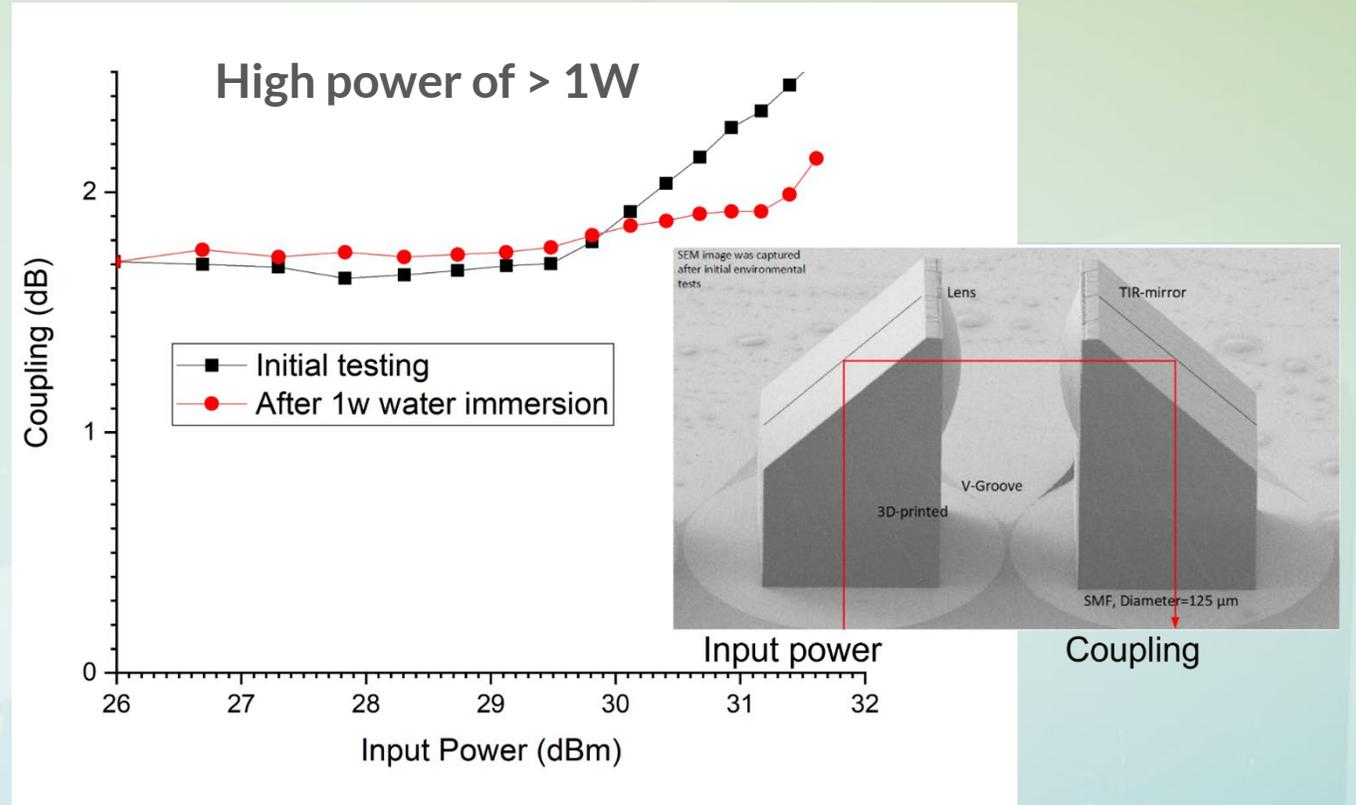
Reliability



Connection (Lens Pair) #	Initially (dB)	400h 85°C/85 rel. hum. (dB)	1840h 85°C/85 rel. hum. (dB)	3960h 85°C/85 rel. hum (dB)
1	1.4	1.4	1.5	1.3
2	1.2	1.2	1.3	1.4
3	1.5	1.6	1.9	1.5
4	1.4	1.6	1.8	1.5
5	1.5	1.6	1.5	1.5

Data: Vanguard Automation, VanCore B

85°C, 85 % rel. hum.; -40/85°C cycle;
10 cycles from -4K to RT, N2 immersion



Industry-proven products, using additive microfabrication

Freeform structure



Fiber array

Reproducible beam
shaping



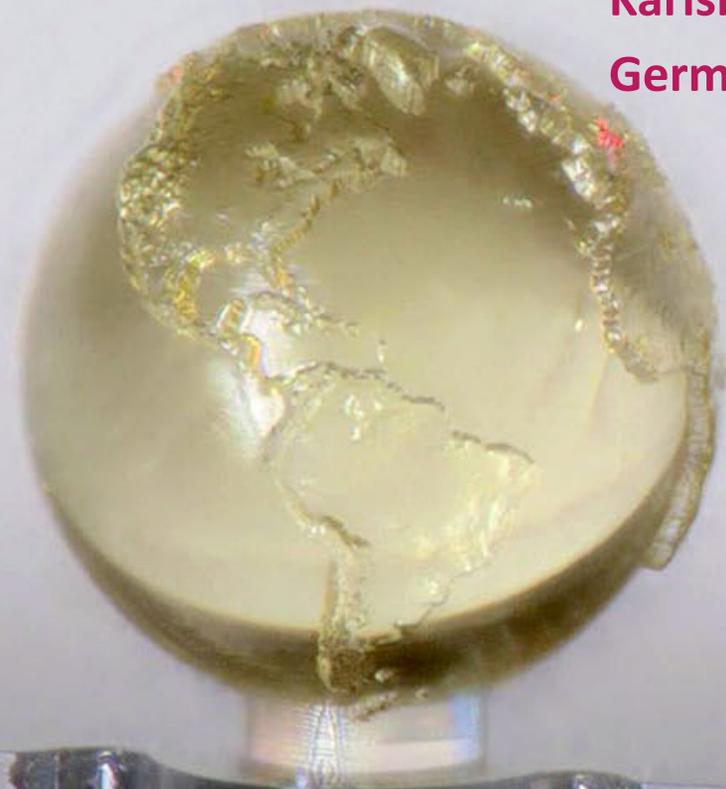
Freeform optics

High precision
alignment

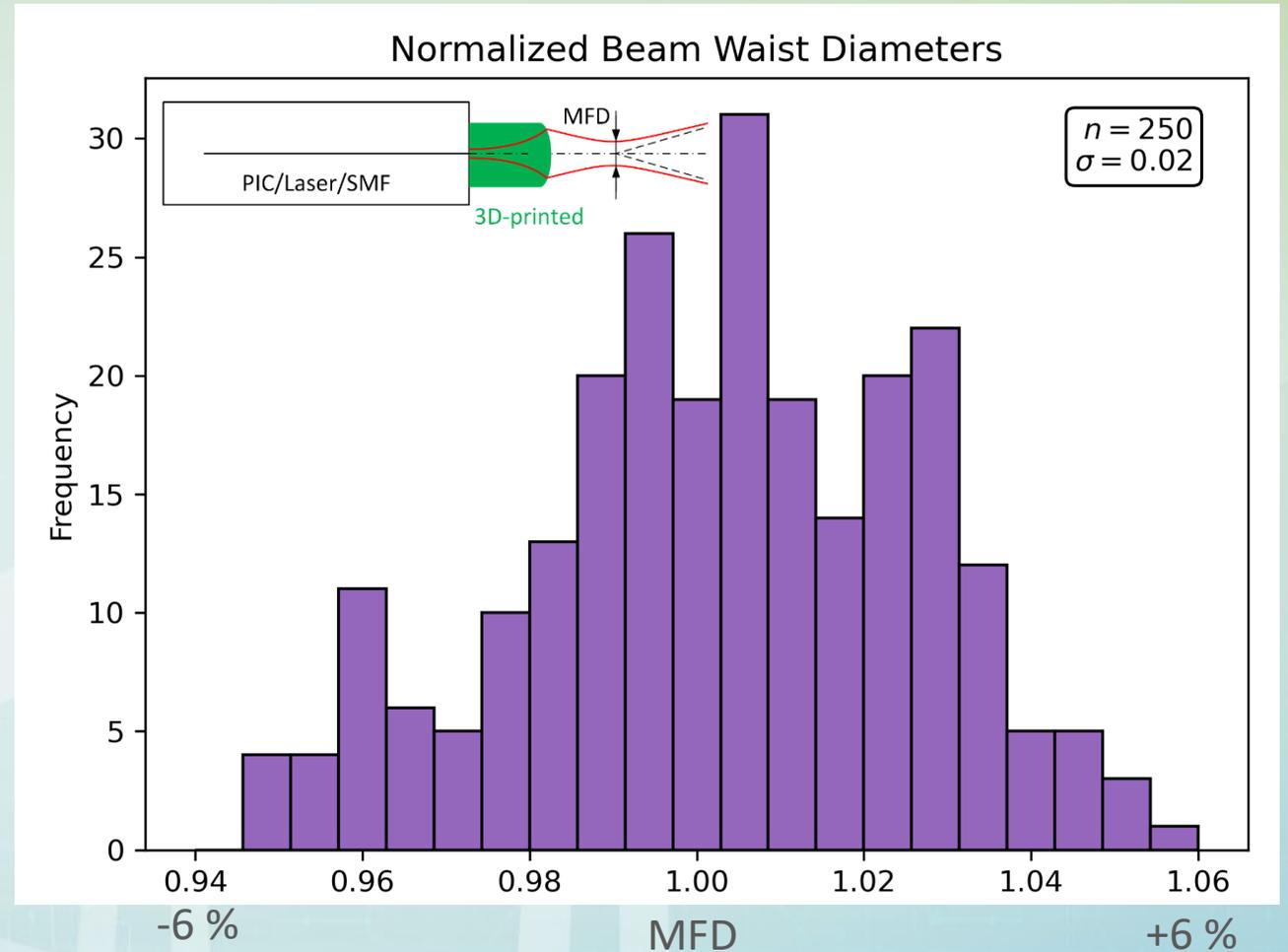
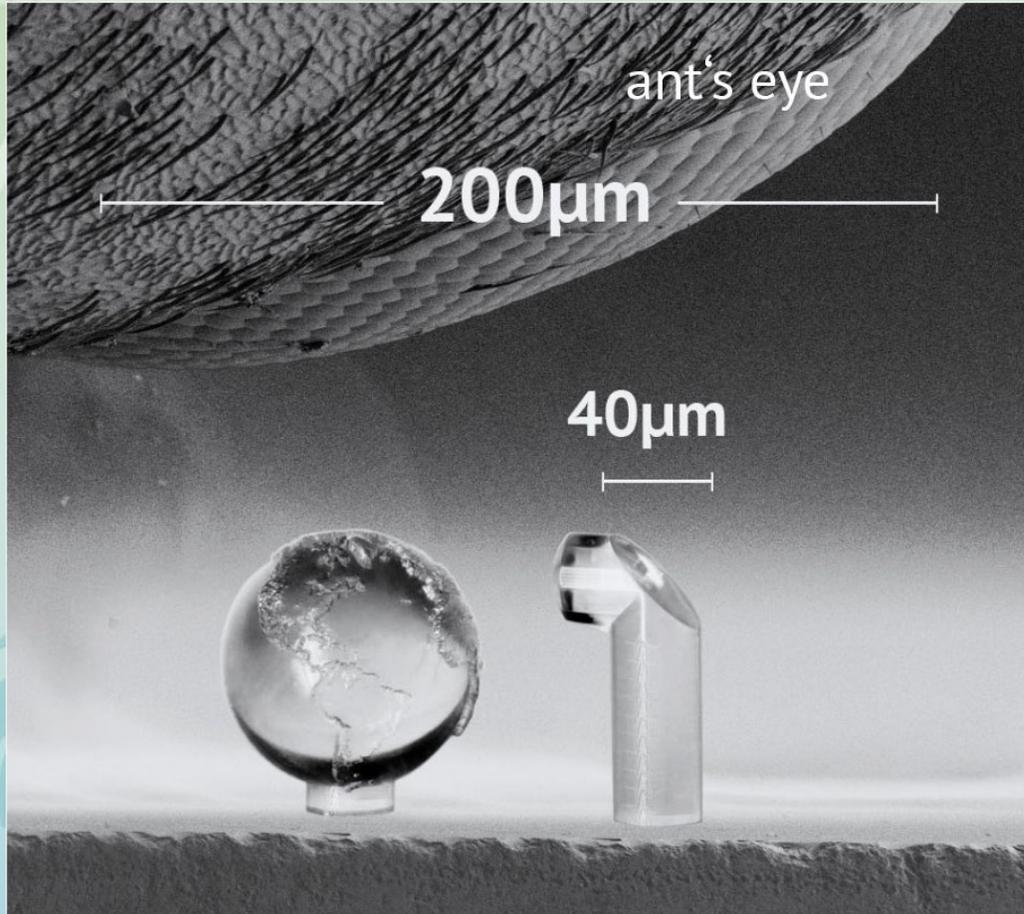
Unedited
picture

Real focus at
Karlsruhe,
Germany

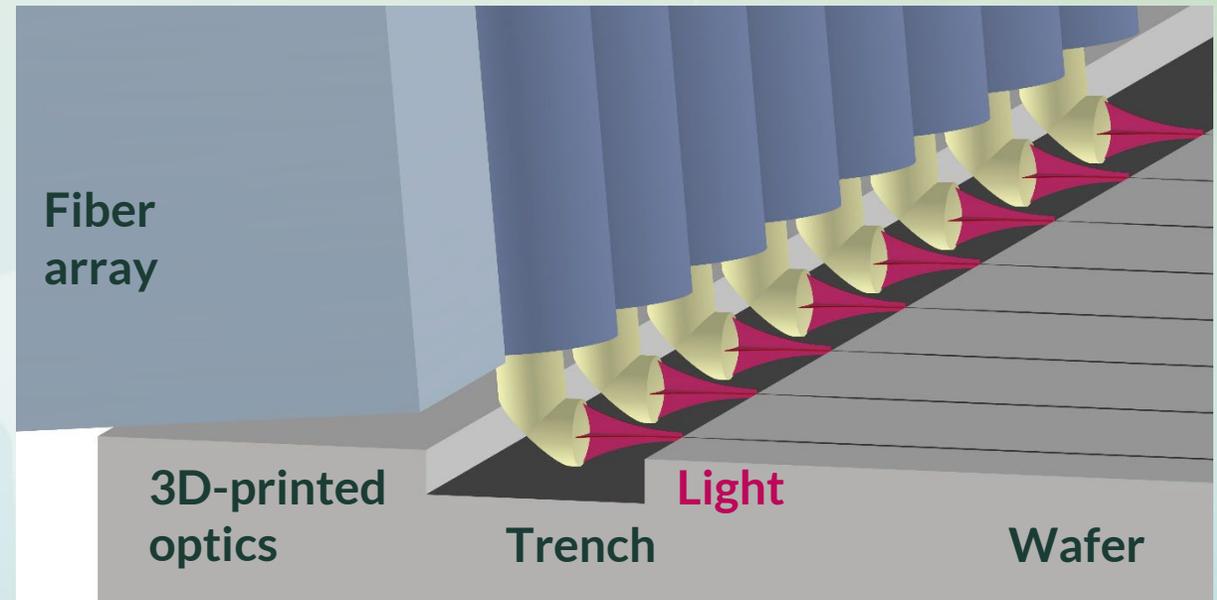
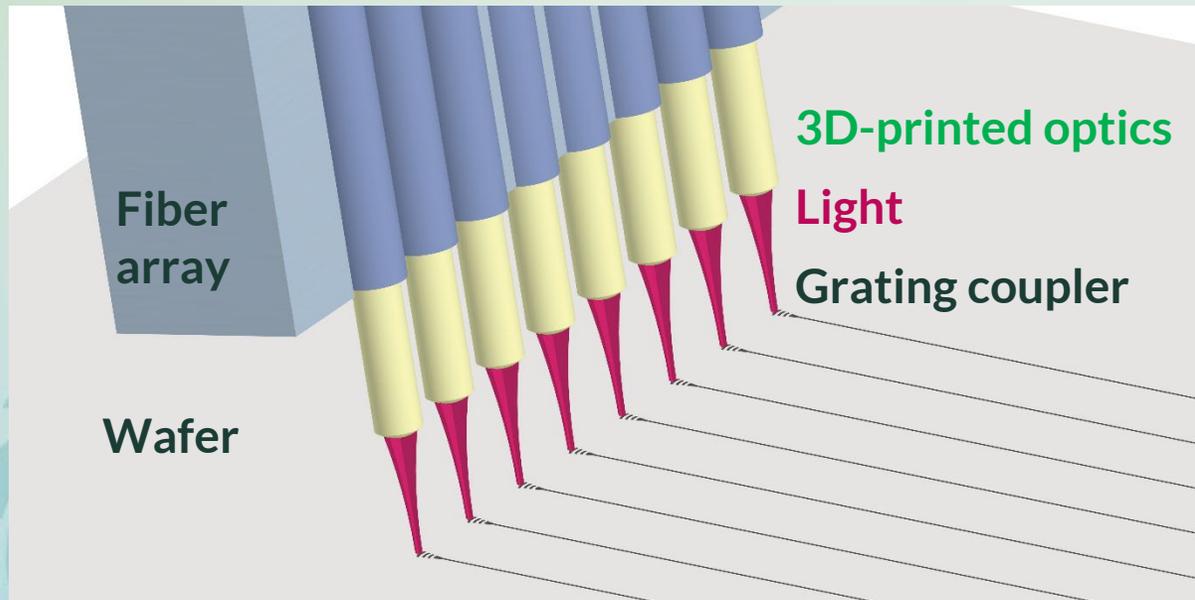
Keystone
photonics



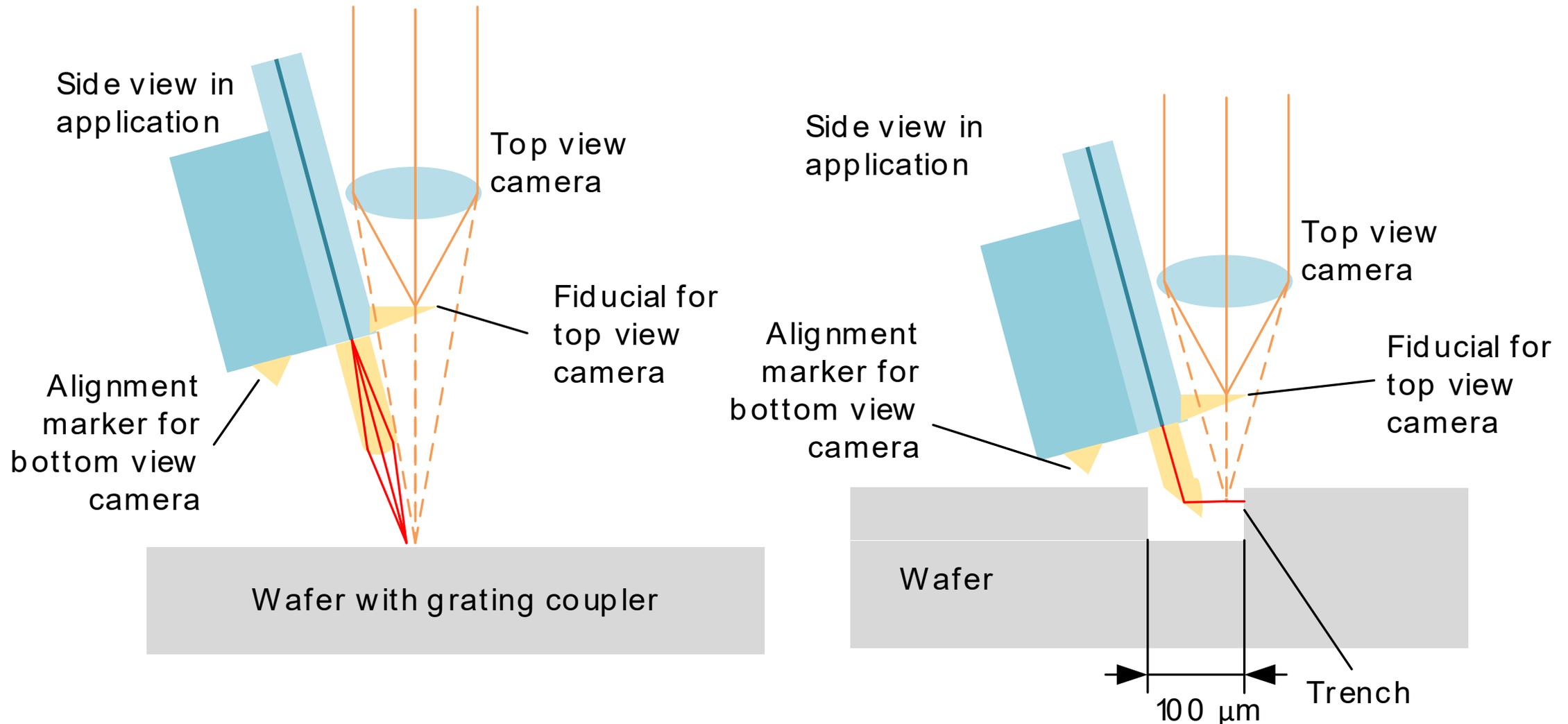
Small & precise



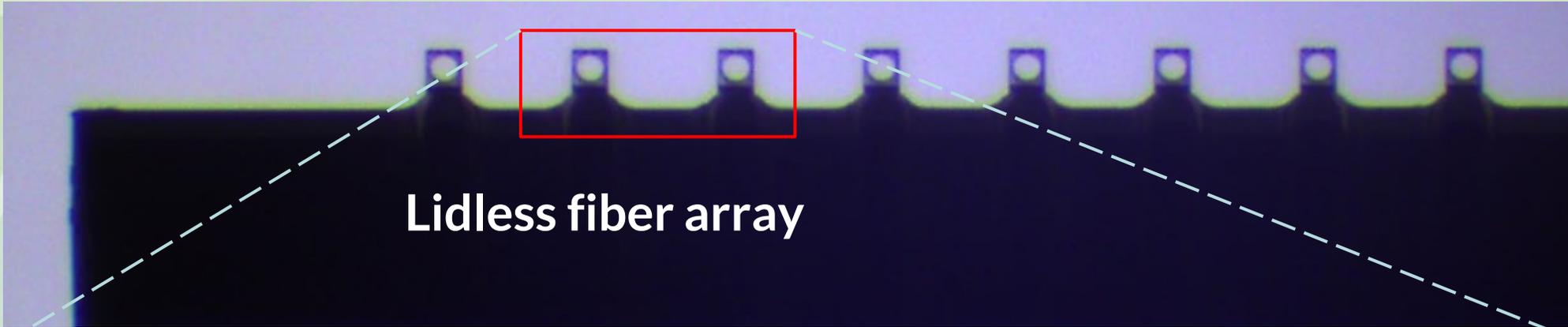
Application: Wafer-level testing in manufacturing



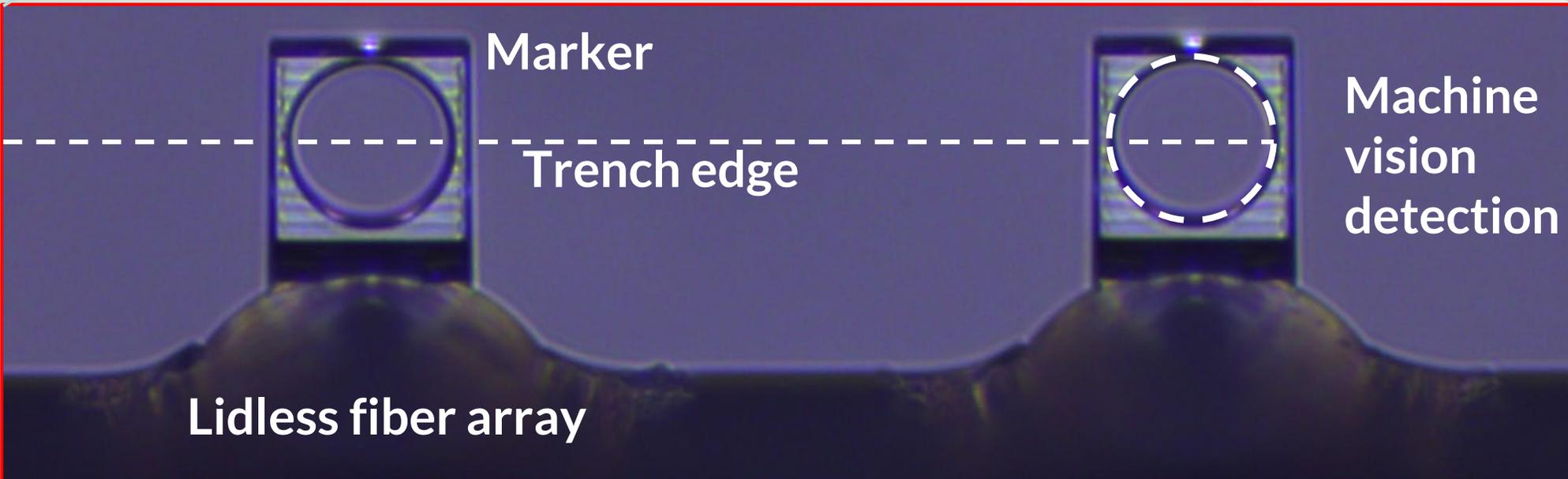
Integration in wafer level tester



Marker structure for alignment

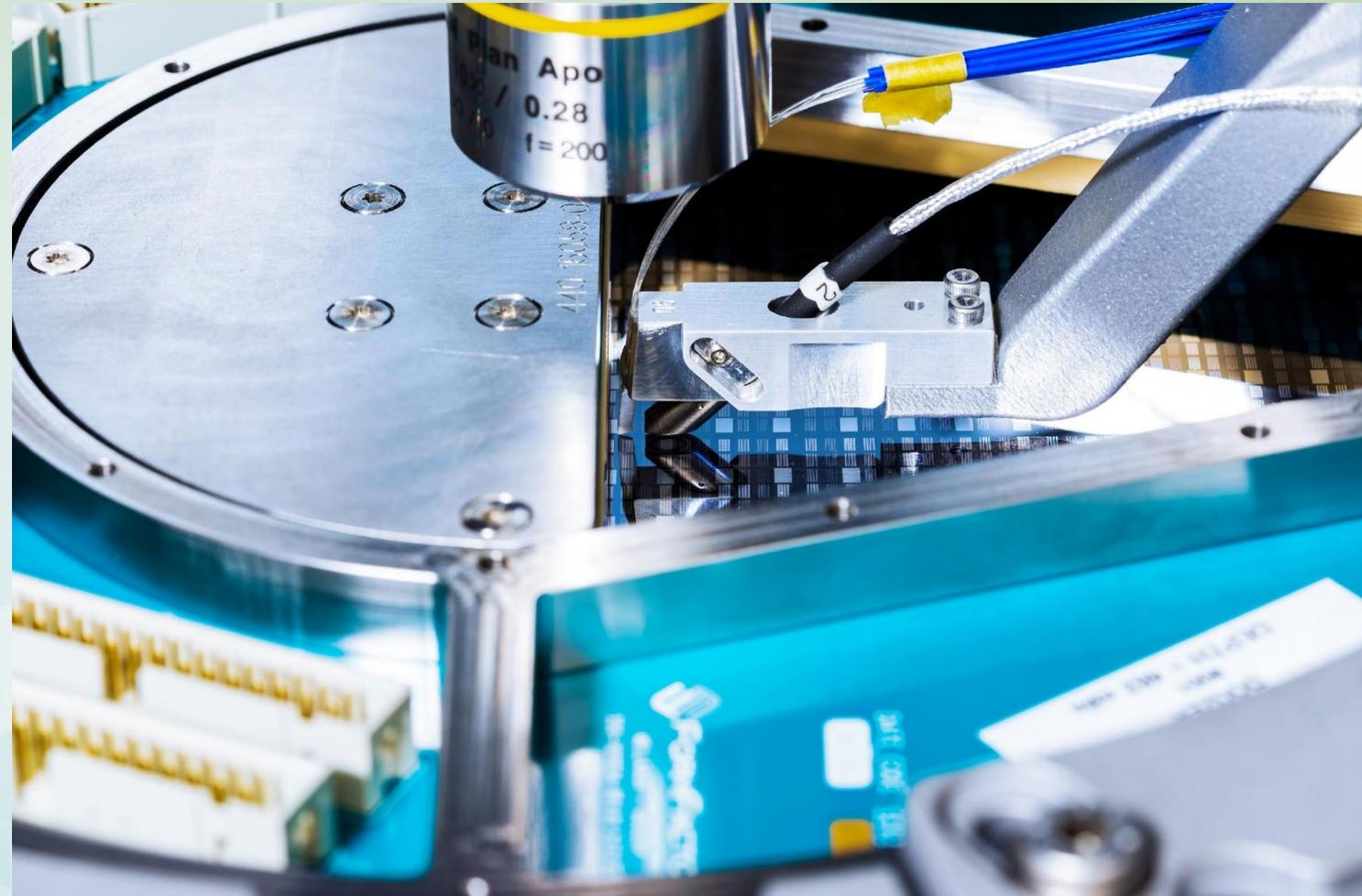
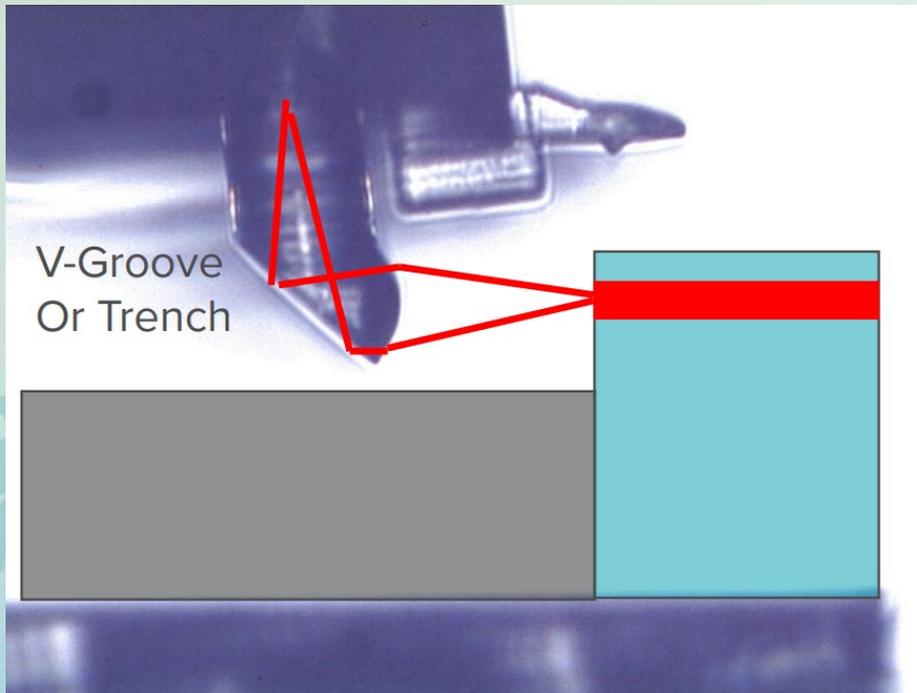


Top-view camera perspective



Formfactor's Pharos Probes

WD=5um (Cleave fiber array)
coupling loss is 4.25 dB/facet
WD=38um (Pharos Lens)
coupling loss is 1.47dB/facet

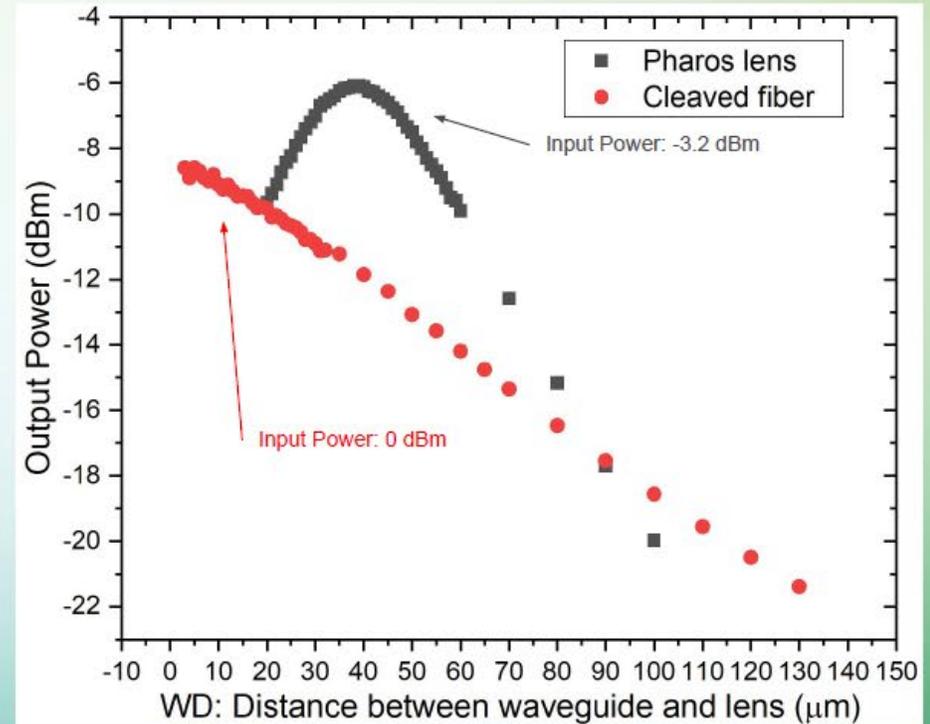
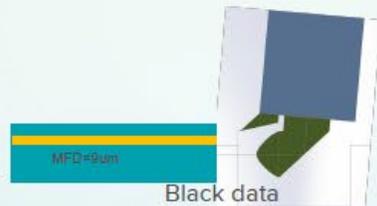
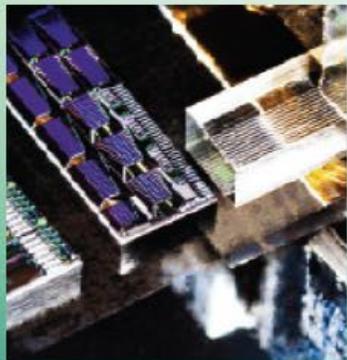


<https://www.formfactor.com/download/fully-automated-integrated-silicon-photonic-wafer-test/?wpdmdl=82376>

Pharos Low Loss Lens Performance for Edge Coupling



Singulated Chip: Chip1 MFD = 9 μm
 FF Pharos Lens: MFD = 6.0 μm
 Structure: Loopbacks Edge Facet
 Best coupling: WD=5 μm (Cleave fiber array) Power = -8.5 dBm
 Coupling loss is 4.25 dB/facet
 WD=38 μm (**Pharos Lens**) Power = 6.01-3.2 dBm
 Coupling loss is **1.47dB/facet**



Comparison with conventional technology

Keystone probes

advantage

reproducible

detect device variation

multi channel

fast

good coupling

BER testing

fiducial

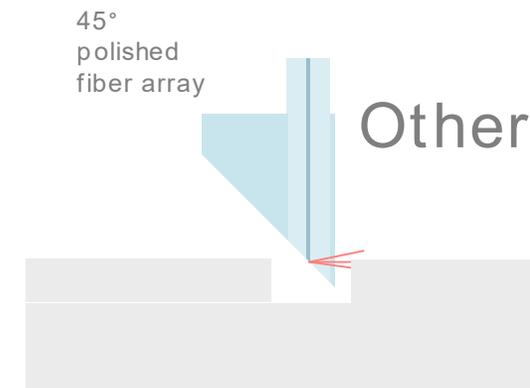
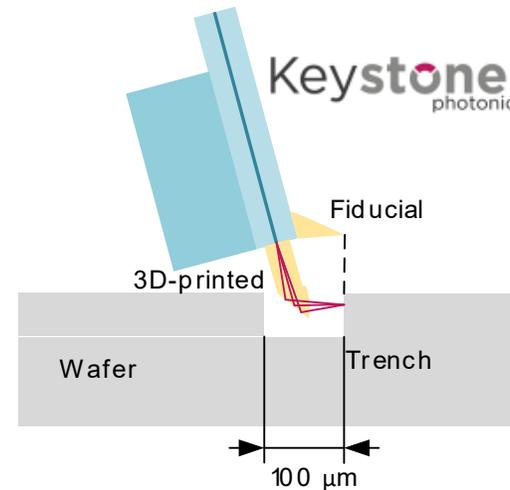
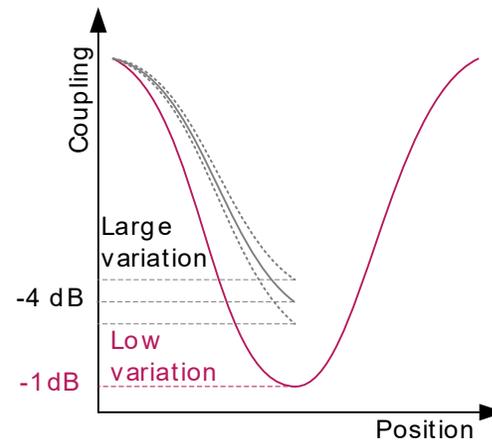
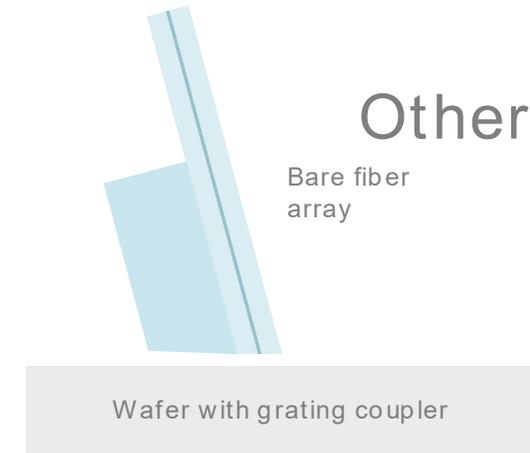
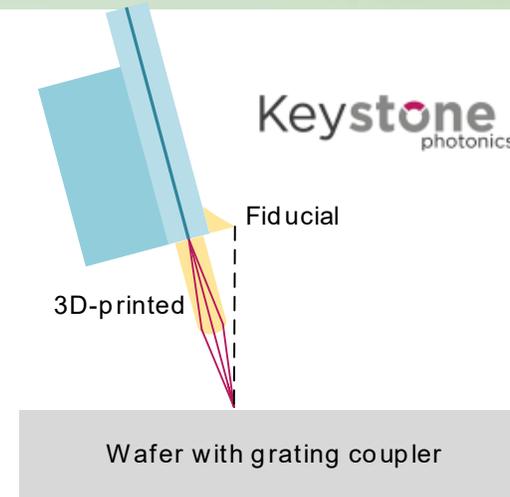
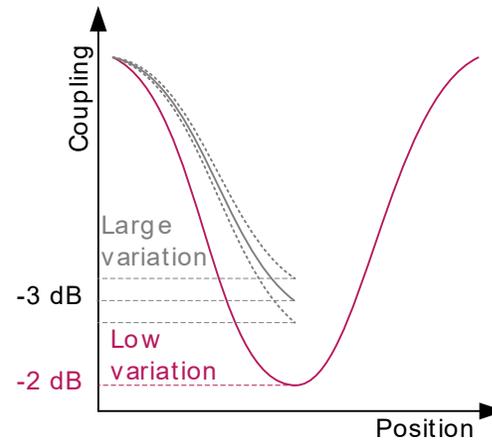
simple alignment

PM-option

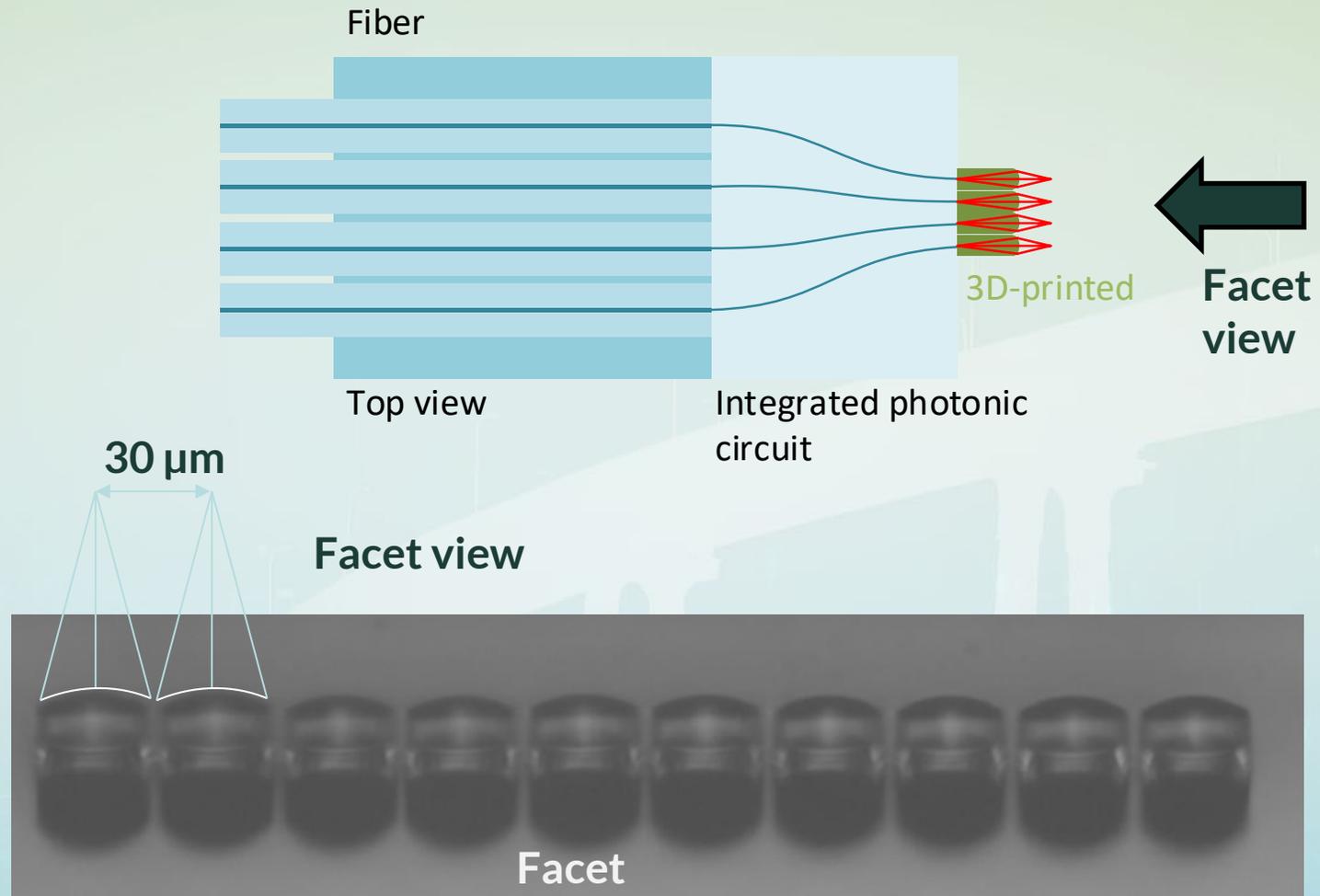
no PM alignment

large working distance

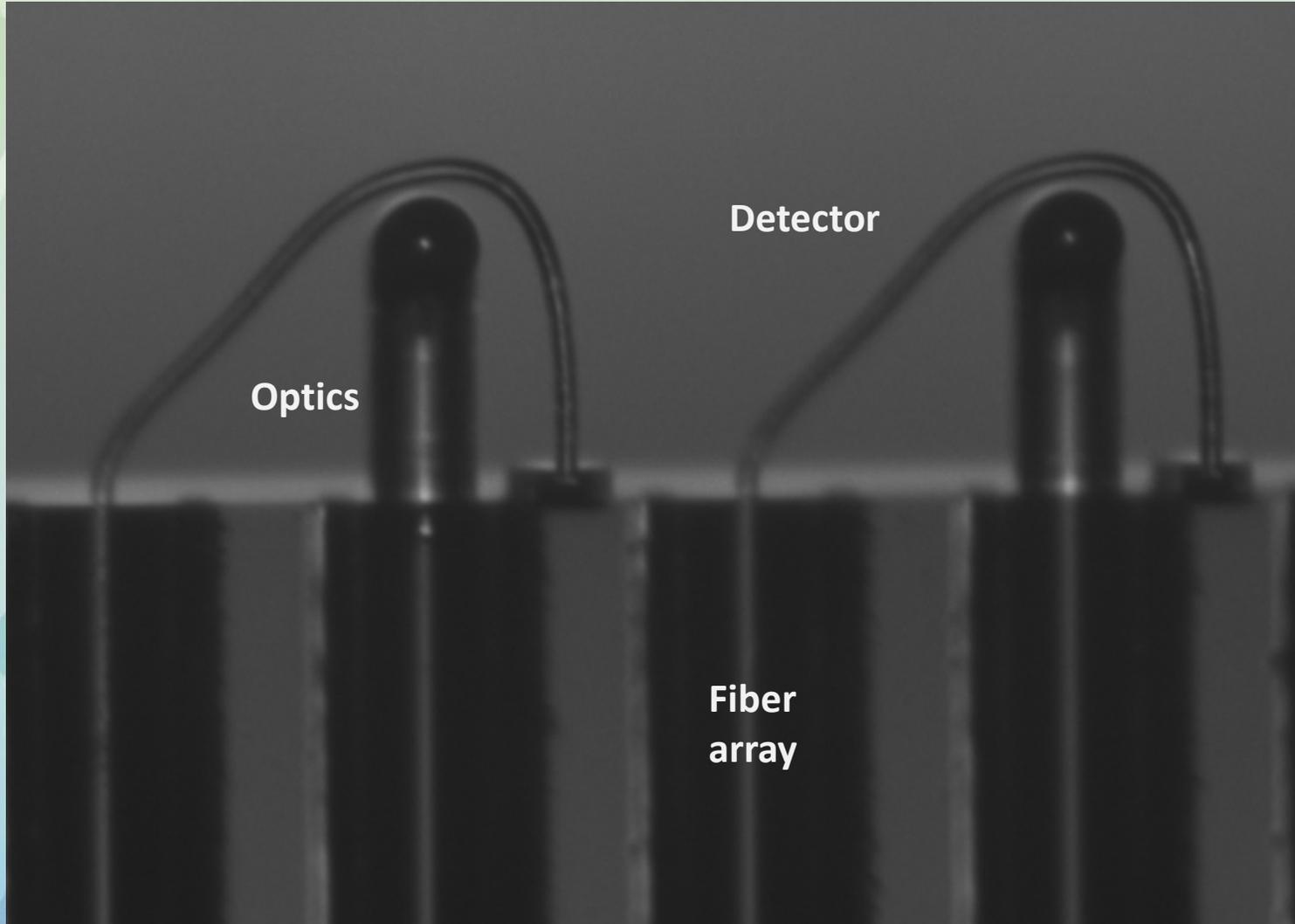
robust testing method



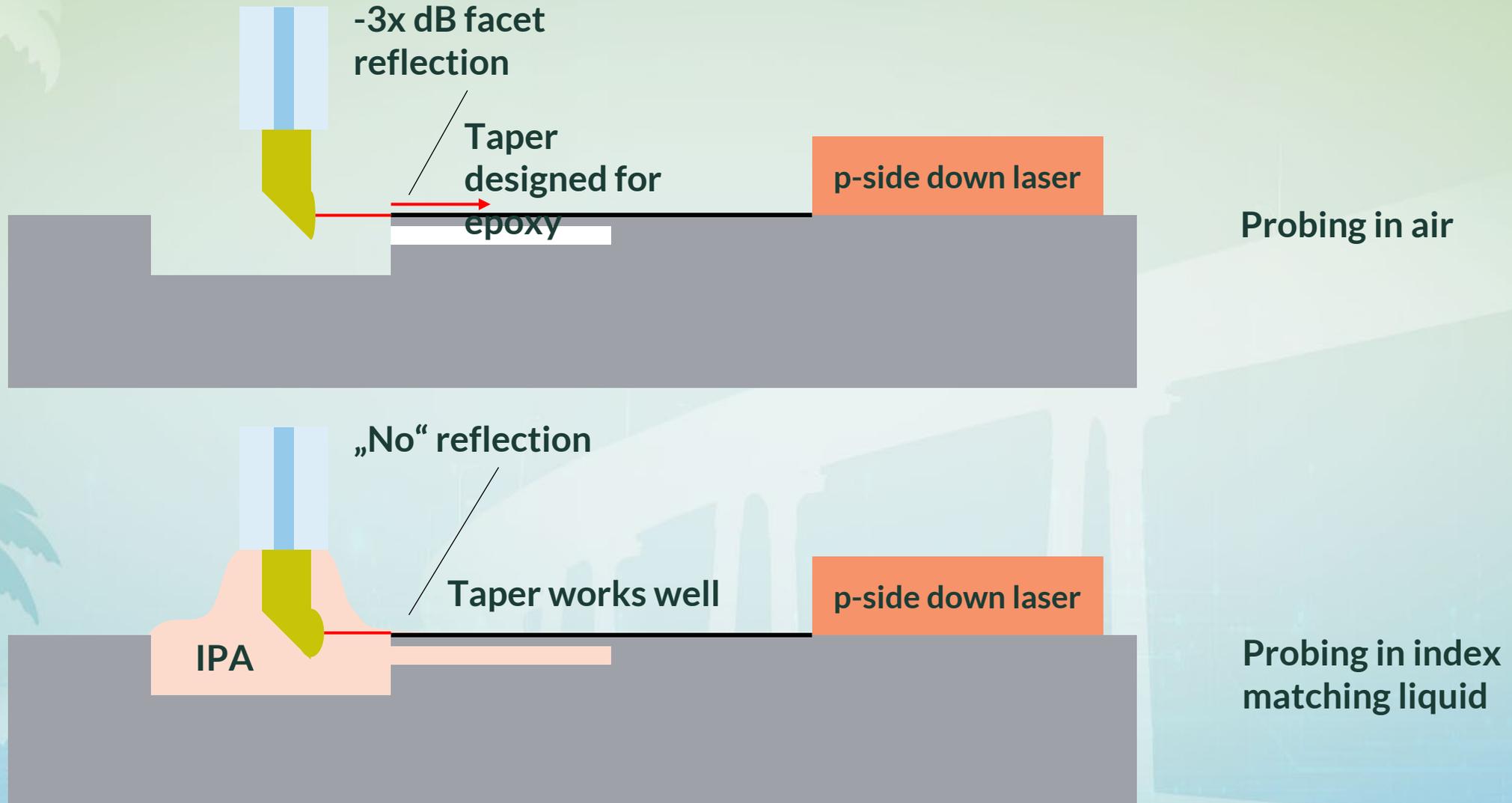
New: Ultra dense pitch testing for AI



New: sensor functionality for production

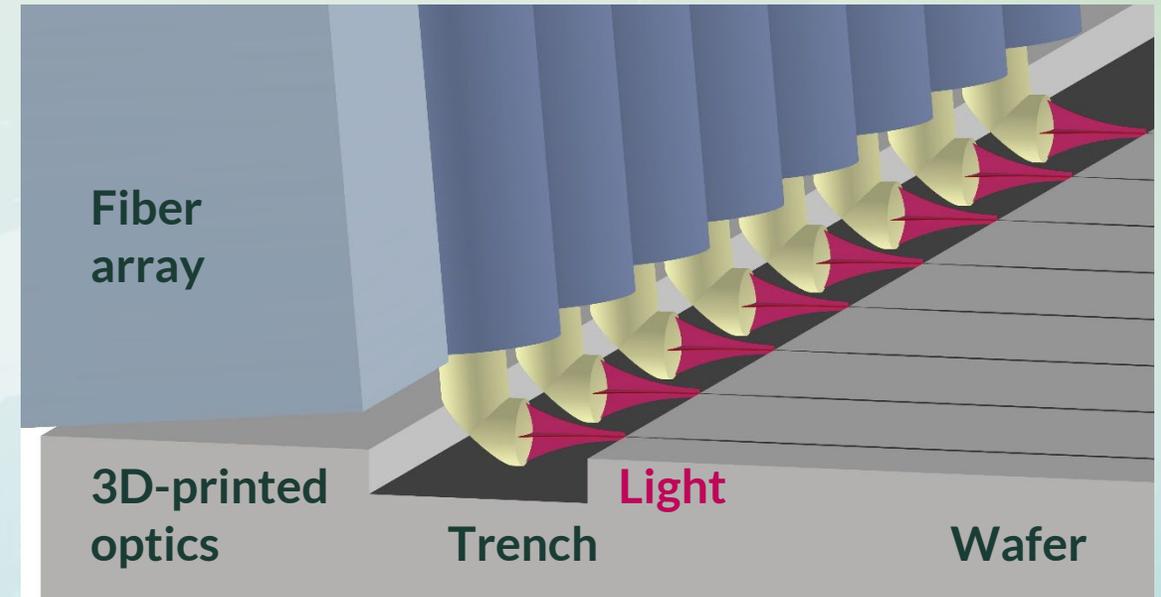


New: Probing in Index Matching Liquid



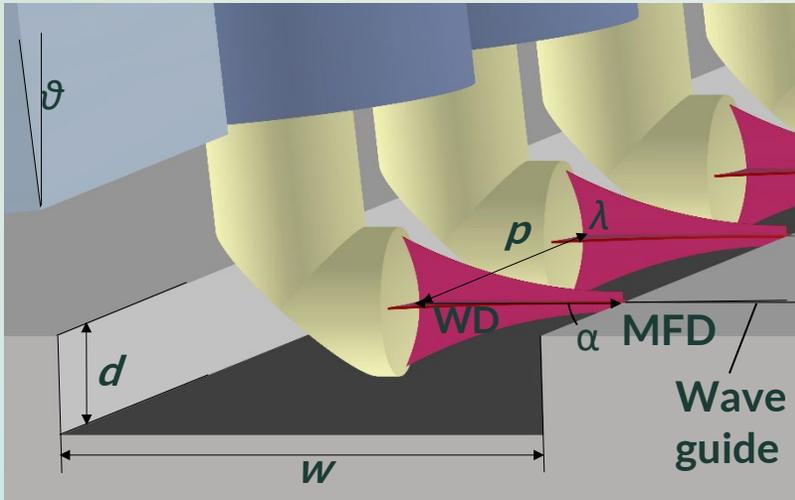
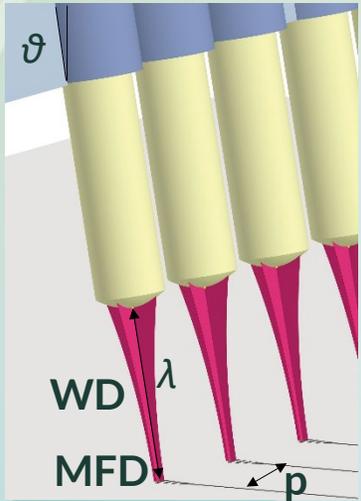
Summary

- **Universal solution for optical wafer level testing**
- **Fabrication is precise and reliable**
 - No offset between localization and fabrication
 - Technology is used in commercial transceivers
- **New developments**
 - Narrow pitch
 - In-built detector
 - Testing in liquid



Annex

Parameters



Name	Range	Accuracy
Fiber type	SMF/PMF/MMF/mixed	$\pm 5^\circ$ (PMF)
Fiber array angle	ϑ from 0 to 12°	
Working distance	WD 15..200 μm	$\pm 10\%$
Mode-field dia.	MFD 2 μm ...30 μm , @1/e ²	$\pm 5\%$, 3 σ
Pitch	p 20 μm .. >1mm	$\pm 1 \mu\text{m}$, 4 σ
Wavelength	λ 1.2 to 1.6 μm	-
Min trench depth	d 30 μm	-
Min trench width	w 100 μm	-
Emission angle**	α 70 $^\circ$ to 110 $^\circ$	$\pm 0.2^\circ$
Coupling*	<-1dB	$\pm 0.2 \text{ dB}, \sigma$
Reflection	- < -33 dB	
Operation temp.	- 4K to 85 $^\circ\text{C}$	-
Acceleration	Shock 500g, vib. 20g	
Max. power	1 W, cw @ 1550nm	
Channel count	Up to 64	

*Depending on PIC mode-field **Emission angle can range from 70 $^\circ$ to 110 $^\circ$ in plane and 88 $^\circ$ (<90 $^\circ$ => towards wafer) to 110 $^\circ$ out of plane

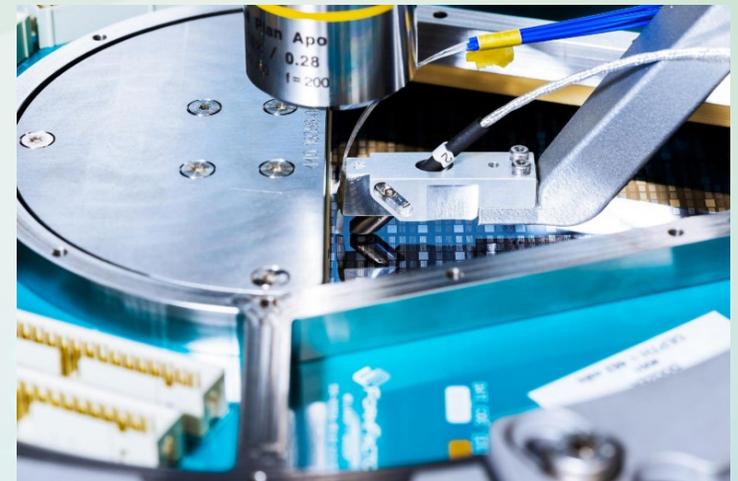
Engagement



corpus type A corpus type B corpus type C corpus type D

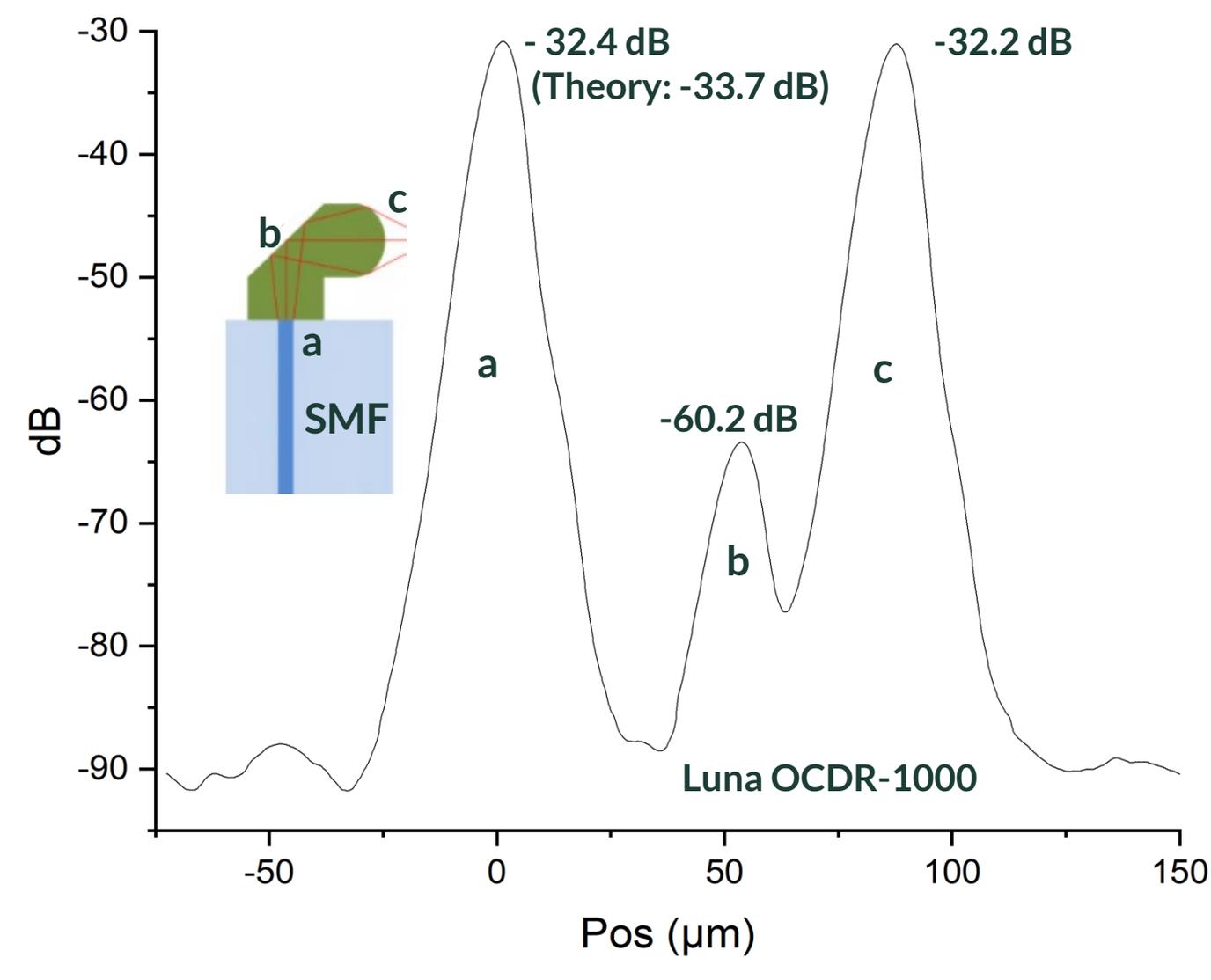
please select features

- choose corpus type *
- wavelength *
- eMail *
- additional message



sales@keystone-photonics.com
www.keystone-photonics.com

Back reflection



Ready for quantum application @Cryo



image source: KIT

- **Complete package**
 - 3D-printed freeform optics
 - Application specific products
- **Suitable for cryogenic temperature**
 - Operation at 4K
 - 4K to room temperature (>10 cycles)
 - Stable @ liquid N2 immersion
 - Wavelength 530 nm to > 2000 nm
- **What we can do**
 - 3D micro-structures for mdB coupling
 - Test & Measurement

sales@keystone-photonics.com

www.keystone-photonics.com

Datasheet photoresist VanCore B*

- compatible components
 - laser (DFB and other)
 - PIN and APD diodes
 - SMF, PMF and MMF fiber arrays
 - PIC: SOI, SiN, InP, LiNb and more
- standard building blocks:
 - lenses with focal length up to centimeters and mode-field diameters of 2.0 μm to 100 μm (@1/e² intensity)
 - total-internal-reflection mirrors
 - 3D-printed mode-size converter
- coupling, depending on laser and chip
 - laser-to-chip: 0.6 to 2.5 dB
 - chip-to-fiber: 1.5 to 2.5 dB,
- alignment tolerances @ 1 dB penalty:
 - $\pm 1.5 \mu\text{m}$ (single lens on one component) to $\pm 15 \mu\text{m}$ (beam expander)
- operation range
 - 530 nm to 1650 nm
- reproducibility
 - below $\sigma = 0.2$ dB coupling variation
 - below 10% mode-field and focus length variation/deviation
- accuracy
 - below $\sigma = 50$ nm detection accuracy
 - below ± 100 nm shape accuracy
 - less than 10 nm RMS-roughness
- reliability testing
 - > 4000 h 85°C/85% rel. hum
 - > 250 cycles -40°C to 85°C
 - reflow soldering, 3 cycles, 270°C
 - AuSn 310°C
- shock testing
 - acceleration of up to 1500 g
 - vibration, 20g, all axis
- high power operation
 - >1 W @ 1550 nm
- cryogenic operation
 - > 10 cycles 4K to room temperature



our production solution:
Vanguard Automations
SONATA1000

*by Vanguard
Automation GmbH

Printing process of lenses with Sonata1000

